

ABSTRACT OF THE INVENTION

The invention relates to a conducting structure of a multi-layers
5 IC board, which includes conducting rod being received in aperture of the
IC board to obtain an effective connection and conduction. And the
conducting wire is placed horizontally on the IC board, which has its
ending pin and annular metal ring to contact with two apertures
respectively and to be welded thereon for perfect conduction and smaller
10 assembled volume.